



Device and Integration Technology of Microelectronics

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Deadline for manuscript
submissions:

closed (20 June 2023)

Message from the Guest Editors

The basic and core content of microelectronics is the semiconductor devices. These devices help with miniaturization and integration through advanced integration technology.

This Special Issue intends to present new ideas and experimental results in the field of advanced devices and integration technology of microelectronics, evolving it from theories, simulations, processes and experiments to practical uses.

- Advances in various conventional micro/nanoelectronic devices (optoelectronics, power devices, sensors, bioelectronics, etc.).
- Emerging micro/nanoelectronic devices and physics (tunnel FET, 2D materials, CNTs, nanowires, etc.).
- Device and integration technology of memory, including advances in both conventional memories (SRAM, DRAM and Flash) and emerging memories (RRAM, MRAM, PRAM and FeRAM).
- Integration technology of microelectronics (2.5D/3D)/heterogeneous integration, novel integration schemes for advanced nodes, integrated implementations of power/optical/biodevices, etc.).
- Electrical and physical characterization, reliability evaluation and yield analysis of device and integration technology of microelectronics.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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